



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SC-89</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	160	80 000	200 °C + N2	0	0.00
HAST	1705	180 500	130 °C, 85 % RH	0	0.00
Pressure Pot	3505	355 680	121°, 15 PSIG	0	0.00
Solder DUNK	330	990	260 °C, 10 s	0	0.00
Solderability	500	1060	883 M2003	0	0.00
Temp. Cycle	6205	323 500	- 65 °C to 150 °C	0	0.00